

## **AMENDMENTS TO THE CLAIMS**

- 1. (Withdrawn)** A substrate processing method, comprising:  
carrying out a cleaning treatment and a catalyst-imparting treatment of a surface of a substrate as pre-plating treatments; and then  
electroless plating a metal film on the catalyst-imparted surface of the substrate,  
wherein the cleaning treatment is carried out in a wider area of the surface of the substrate than that area to which a catalyst is imparted by the catalyst-imparting treatment.
- 2. (Withdrawn)** The substrate processing method according to claim 1, wherein the cleaning treatment as a pre-plating treatment comprises pre-cleaning prior to the catalyst-imparting treatment and cleaning after the catalyst-imparting treatment.
- 3. (Withdrawn)** The substrate processing method according to claim 1, wherein the area of the surface of the substrate to which a catalyst is imparted by the catalyst-imparting treatment is the same as that area for which uniform plating is necessary.
- 4. (Withdrawn)** The substrate processing method according to claim 3, wherein the cleaning treatment as a pre-plating treatment comprises pre-cleaning prior to the catalyst-imparting treatment and cleaning after the catalyst-imparting treatment.
- 5. (Withdrawn)** A substrate processing apparatus, comprising:  
a cleaning treatment unit for carrying out a cleaning treatment of a substrate; and  
a catalyst-imparting treatment unit for carrying out a catalyst-imparting treatment of the substrate,  
wherein said respective treatment is carried out as a pre-plating treatment by allowing the surface of the substrate to be in contact with a respective pre-plating treatment liquid while sealing a peripheral portion of the surface of the substrate with a seal ring, the cleaning treatment unit being

designed to carry out the cleaning treatment in a wider area of the surface of the substrate than that area to which a catalyst is imparted in the catalyst-imparting treatment unit.

6. **(Withdrawn)** The substrate processing apparatus according to claim 5, wherein the cleaning treatment unit and the catalyst-imparting treatment unit have the same construction except that the seal rings have different opening areas.

7. **(Withdrawn)** The substrate processing apparatus according to claim 5, wherein the area of the surface of the substrate to which a catalyst is imparted in the catalyst-imparting treatment unit is the same as that area for which uniform plating is necessary.

8. **(Withdrawn)** The substrate processing apparatus according to claim 7, wherein the cleaning treatment unit and the catalyst-imparting treatment unit have the same construction except that the seal rings have different opening areas.

**9-13. (Canceled)**

14. **(Currently Amended)** A substrate processing unit that includes:

a substrate receiving ring to which a seal ring is mounted;

a vertically movable substrate holder having a substrate fixing ring movable so as to hold a substrate by nipping a peripheral portion of the substrate between the substrate fixing ring and the seal ring to seal the peripheral portion of the substrate during processing of the substrate; and

a temporary retaining section, that is mounted to the substrate receiving ring and positioned around the seal ring to temporarily retaining the substrate thereon while forming a space between the substrate and the seal ring;

wherein the substrate receiving ring and the substrate fixing ring hold the substrate with its front surface facing downward; and

wherein the temporary retaining section is comprised of a plurality of temporary retaining pins which are biased upwardly by an elastic member, and which lower integrally with the substrate holder against the

elastic force of the elastic member as the substrate holder lowers, and return to the original position as the substrate holder rises; and

wherein each of the temporary retaining pins has a head portion having a tapered surface provided so that, when placing the substrate on the temporary retaining pins, the tapered surface contacts a peripheral end surface of the substrate and effects positioning of the substrate, and having a retaining portion, projecting outwardly, for receiving thereon and retaining a peripheral lower surface of the substrate.

**15. (Previously Presented)** The substrate processing unit according to claim 14, wherein the substrate processing unit is a pre-plating treatment unit for carrying out a pre-plating treatment of the substrate prior to plating.

**16. (Original)** The substrate processing unit according to claim 15, wherein the pre-plating treatment unit is a catalyst-imparting treatment unit for imparting a catalyst to the surface of the substrate.

**17. (Original)** The substrate processing unit according to claim 15, wherein the pre-plating treatment unit is a cleaning treatment unit for cleaning the surface of the substrate.

**18-21. (Canceled)**

**22. (New)** A substrate processing unit according to claim 14, wherein said retaining portion of said head portion projects outwardly of said tapered surface in a horizontal direction.

**23. (New)** A substrate processing unit according to claim 14, wherein said head portion has a flat top surface, with said tapered surface extending from said flat top surface outwardly to said retaining portion, and said retaining portion projecting outwardly, in a horizontal direction, of said tapered surface.